

November 2013

# FQP10N60C / FQPF10N60C N-Channel QFET® MOSFET

# 600 V, 9.5 A, 730 m $\Omega$

# **Description**

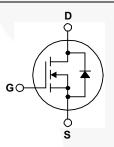
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology. This advanced technology has been especially tailored to mini-mize on-state resistance, provide superior switching perfor-mance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high effi-ciency switched mode power supplies, active power factor correction, electronic lamp ballasts based on half bridge topology.

# **Features**

- 9.5 A, 600 V,  $R_{DS(on)}$  = 730 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 4.75 A
- · Low Gate Charge (Typ. 44 nC)
- · Low Crss (Typ. 18 pF)
- 100% Avalanche Tested







# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FQP10N60C	FQPF10N60C	Unit
V <sub>DSS</sub>	Drain-Source Voltage		6	600	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25	5°C)	9.5	9.5 *	Α
	- Continuous (T <sub>C</sub> = 10	00°C)	5.7	5.7 *	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	38	38 *	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30		٧
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2		700		mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	9.5		Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		15.6		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		156	50	W
	- Derate above 25°C		1.25	0.4	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150		°C
T <sub>L</sub>	Maximum lead temperature for soldering, 1/8" from case for 5 seconds		300		°C

<sup>\*</sup> Drain current limited by maximum junction temperature.

#### **Thermal Characteristics**

Symbol	Parameter	FQP10N60C	FQPF10N60C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.8	2.5	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	62.5	°C/W

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP10N60C	FQP10N60C	TO-220	Tube	N/A	N/A	50 units
FQPF10N60C	FQPF10N60C	TO-220F	Tube	N/A	N/A	50 units
FQPF10N60CT	FQPF10N60CT	TO-220F	Tube	N/A	N/A	50 units
FQPF10N60C_F105	FQPF10N60C	TO-220F	Tube	N/A	N/A	50 units

# Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Characte	eristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 μA, Referenced to 25°C	-	0.7		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	<i>A</i>		1	μΑ
	V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C				10	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$	\		-100	nA
On Characte	ristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.75 A		0.6	0.73	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 4.75 A		8.0		S
	mic Characteristics			1570	2040	pF
C <sub>iss</sub>	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		166	2040	рF
C <sub>rss</sub>	Reverse Transfer Capacitance			18	24	pF
orss	reverse transfer capacitance			10	27	Pi
Switching C	haracteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 9.5A,	- /	23	55	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega$	/	69	150	ns
$t_{d(off)}$	Turn-Off Delay Time			144	300	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		77	165	ns
$Q_g$	Total Gate Charge	$V_{DS} = 480 \text{ V}, I_{D} = 9.5\text{A},$		44	57	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		6.7		nC
$Q_{gd}$	Gate-Drain Charge	(Note 4)		18.5		nC
Drain-Source	e Diode Characteristics and Maximum	Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				9.5	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				38	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 9.5 \text{ A}$			1.4	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 9.5 A,		420		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$		4.2	-	μС

#### NOTES:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 14.2 mH, I  $_{AS}$  = 9.5 A, V  $_{DD}$  = 50 V, R  $_{G}$  = 25  $\Omega,$  starting T  $_{J}$  = 25°C.
- $3.\,I_{SD} \leq 9.5\;\text{A, di/dt} \leq 200\;\text{A/}\mu\text{s, V}_{DD} \leq \text{BV}_{DSS},\;\text{starting}\;\text{T}_{J} = 25^{\circ}\text{C}.$
- 4. Essentially independent of operating temperature typical characteristics.

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

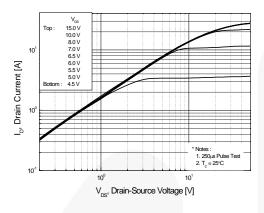


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

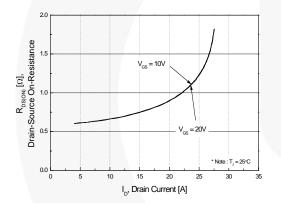


Figure 2. Transfer Characteristics

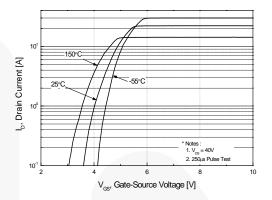


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

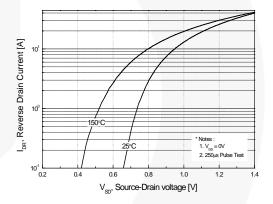
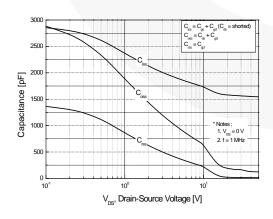
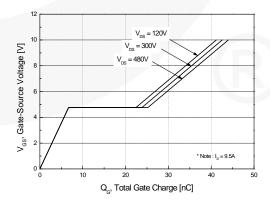


Figure 5. Capacitance Characteristics



**Figure 6. Gate Charge Characteristics** 



# Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

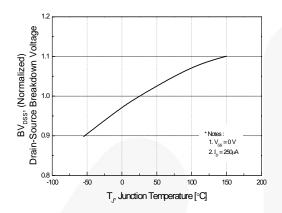


Figure 8. On-Resistance Variation vs. Temperature

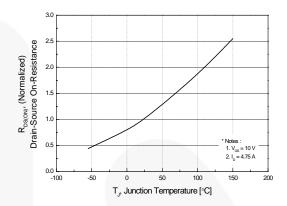


Figure 9-1. Maximum Safe Operating Area for FQP10N60C

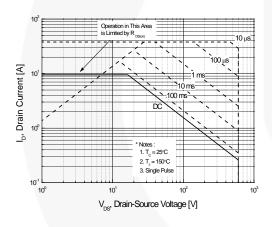


Figure 9-2. Maximum Safe Operating Area for FQPF10N60C

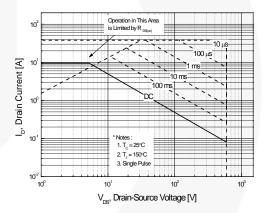
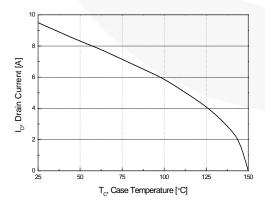


Figure 10. Maximum Drain Current vs. Case Temperature



# Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve for FQP10N60C

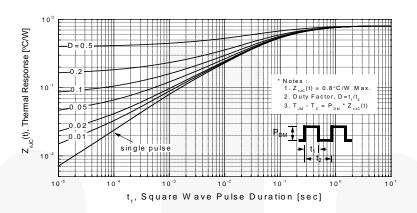
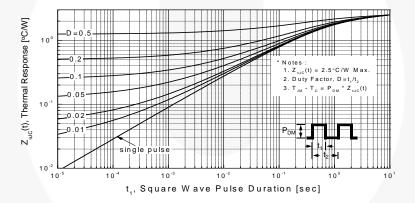


Figure 11-2. Transient Thermal Response Curve for FQPF10N60C



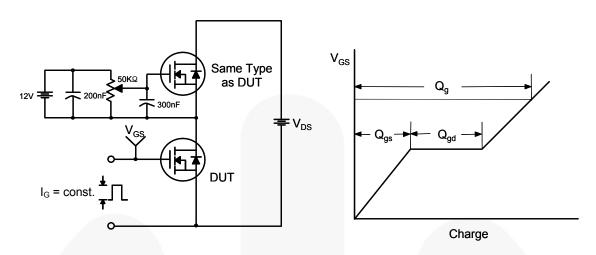


Figure 12. Gate Charge Test Circuit & Waveform

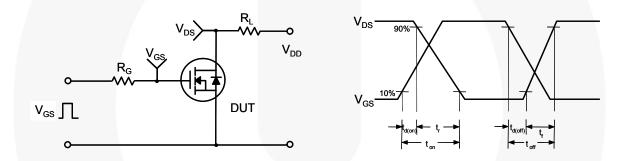


Figure 13. Resistive Switching Test Circuit & Waveforms

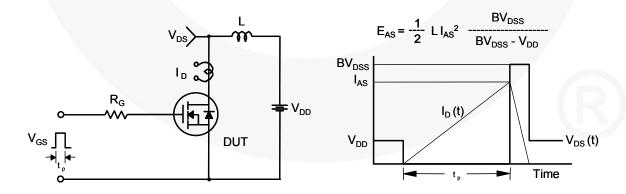


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

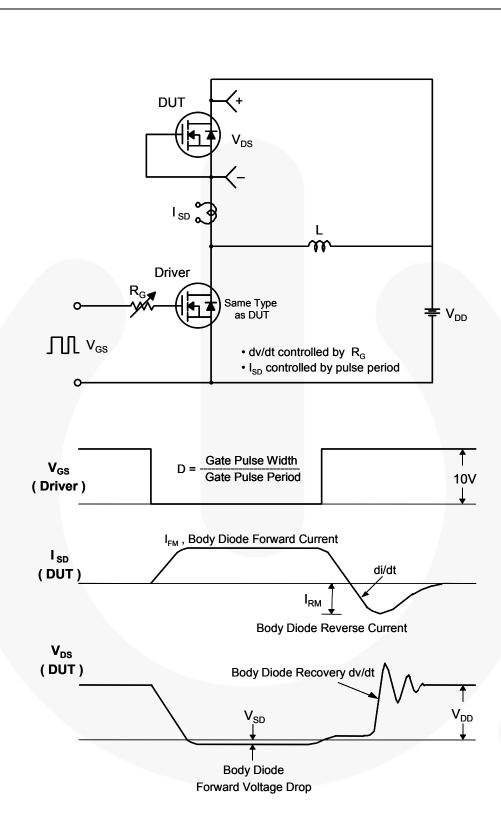


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

## **Mechanical Dimensions**

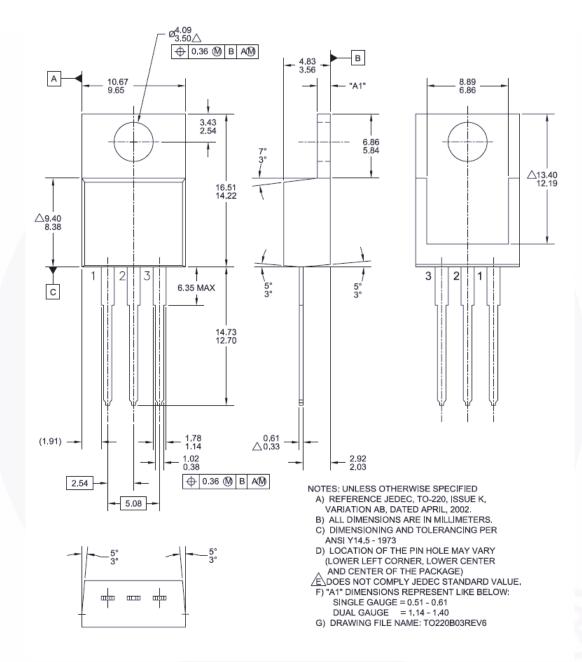


Figure 16. TO-220, Molded, 3-Lead, Jedec Variation AB

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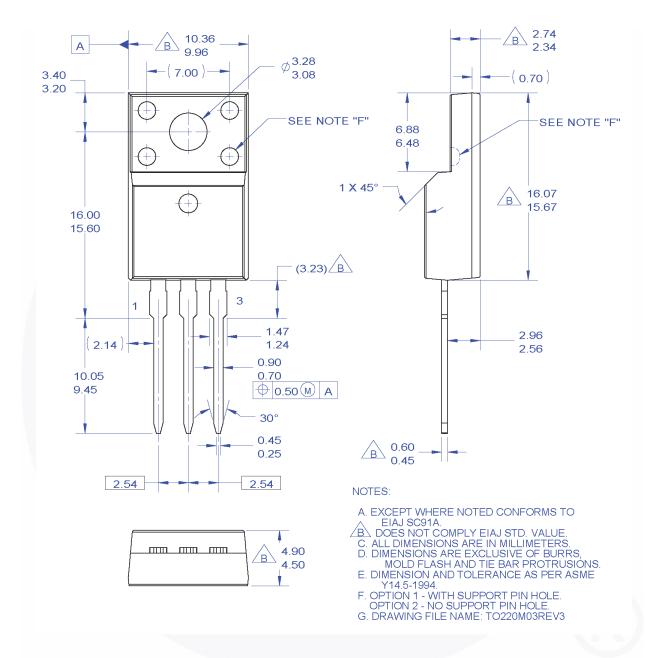


Figure 17. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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